

PATENT ASSIGNMENT COVER SHEET

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SUBMISSION TYPE:	NEW ASSIGNMENT																		
NATURE OF CONVEYANCE:	ASSIGNMENT																		
CONVEYING PARTY DATA																			
<table border="1"> <thead> <tr> <th>Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>EUN JUNG JO</td> <td>03/28/2013</td> </tr> <tr> <td>JIN SUK SON</td> <td>04/08/2013</td> </tr> <tr> <td>JOB HA</td> <td>03/28/2013</td> </tr> <tr> <td>JAE HOON PARK</td> <td>04/08/2013</td> </tr> <tr> <td>CHANG SEOB HONG</td> <td>03/28/2013</td> </tr> <tr> <td>JOON HYUNG CHO</td> <td>04/08/2013</td> </tr> <tr> <td>IN WHA JEONG</td> <td>03/28/2013</td> </tr> <tr> <td>YOUNG HOON KWAK</td> <td>04/08/2013</td> </tr> </tbody> </table>		Name	Execution Date	EUN JUNG JO	03/28/2013	JIN SUK SON	04/08/2013	JOB HA	03/28/2013	JAE HOON PARK	04/08/2013	CHANG SEOB HONG	03/28/2013	JOON HYUNG CHO	04/08/2013	IN WHA JEONG	03/28/2013	YOUNG HOON KWAK	04/08/2013
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RECEIVING PARTY DATA																			
Name:	SAMSUNG ELECTRO-MECHANICS CO., LTD.																		
Street Address:	314, MAETAN 3-DONG, YEONGTONG-GU																		
City:	SUWON, GYUNGGI-DO																		
State/Country:	KOREA, REPUBLIC OF																		
PROPERTY NUMBERS Total: 1																			
<table border="1"> <thead> <tr> <th>Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>29450492</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	29450492														
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Application Number:	29450492																		
CORRESPONDENCE DATA																			
Fax Number:	(202)756-8087																		
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PATENT

NAME OF SUBMITTER:	STEPHEN A. BECKER
Signature:	/STEPHEN A. BECKER/
Date:	01/18/2014
	This document serves as an Oath/Declaration (37 CFR 1.63).
Total Attachments: 4 source=DECLARATIONANDASSIGNMENT#page1.tif source=DECLARATIONANDASSIGNMENT#page2.tif source=DECLARATIONANDASSIGNMENT#page3.tif source=DECLARATIONANDASSIGNMENT#page4.tif	

COMBINED DECLARATION AND ASSIGNMENT FOR PATENT APPLICATION

As a below named inventor, I hereby declare that:

I believe I am the original or an original joint inventor of a claimed invention in the application for which a patent is sought on the invention entitled:

SEMICONDUCTOR DEVICE

attached, or

United States application number or PCT international application
Number 29/450,492 filed on March 18, 2013.

The above-identified application was made or authorized to be made by me.

In the event that the filing date and/or application number are not entered above at the time I execute this document, and if such information is deemed necessary, I hereby authorize and request the registered practitioners of **McDermott Will & Emery LLP**, associated with the Customer Number 20277, to insert above the filing date and/or application number of the application.

I hereby acknowledge that any willful false statement made in this declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

ASSIGNMENT

For good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I hereby assign to


SAMSUNG ELECTRO-MECHANICS CO., LTD.


having an address at 314 Maetan 3-dong, Yeongtong-gu, Suwon, Gyunggi-do, Republic of Korea (hereinafter designated as the Assignee), the entire (100%) right, title and interest for the United States as defined in 35 USC §100, in the invention described in the application identified in this document.

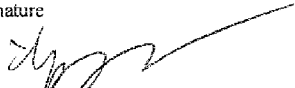
I hereby confirm any prior assignment to Assignee, and to the extent that I have not already done so, agree to assign, and hereby do, sell, assign and transfer unto Assignee and its successors in interest, the full and exclusive right, title and interest in the United States of America, including the right to claim priority under the laws of the United States, the Paris Convention, and any foreign countries, to the inventions as described in the aforesaid application, to the aforesaid application itself, and all divisions, continuations, continuations-in-part, or other applications claiming priority directly or indirectly from the aforesaid application, and any United States or foreign Letters Patent, utility model, or other similar rights which may be granted thereon, including reissues, reexaminations and extensions thereof, and all copyright rights in the aforesaid application and the subject matter disclosed therein, these rights, title and interest to be held and enjoyed by Assignee to the full end of the term for which the Letters Patent, utility model, or other similar rights, are granted and any extensions thereof as fully and entirely as the same would have been held by the undersigned had this assignment and sale not been made, and the right to sue for, and recover for past infringements of, or liabilities for, any of the rights relating to any of the applications, patents, utility models, or other similar rights, resulting therefrom, and the copyright rights;

I hereby covenant and agree to execute all instruments or documents required or requested for the making and prosecution of any applications of any type for patent, utility model, or other similar rights, and for copyright, in the United States and in all foreign countries including, but not limited to, any provisional, continuation, continuation-in-part, divisional, renewal or substitute thereof, and as to letters patent any reissue, re-examination, or extension thereof, and for litigation regarding, or for the purpose of protecting title and to the said invention, the United States application for patent, or Letters Patent therefor, and to testify in support thereof, for the benefit of Assignee without further or other compensation than that above set forth;

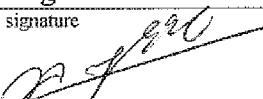
I hereby covenant that no assignment, sale, license, agreement or encumbrance has been or will be entered into which would conflict with this Assignment.

Legal name of first inventor JO, Eun Jung	
First inventor's signature 	Date 2013. 3. 28

Legal name of second inventor SON, Jin Suk	
Second inventor's signature 	Date 2013. 4. 08

Legal name of third inventor HA, Job	
Third inventor's signature 	Date 2013. 3. 28

Legal name of fourth inventor PARK, Jae Hoon	
Fourth inventor's signature 박재훈	Date 2013. 4. 8.

Legal name of fifth inventor HONG, Chang Seob	
Fifth inventor's signature 	Date 2013. 3. 28

Legal name of sixth inventor CHO, Joon Hyung	
Sixth inventor's signature Cho JH.	Date 2013. 4. 8.

Legal name of seventh inventor JEONG, In Wha	
Seventh inventor's signature 정인화	Date 2013. 3. 28

Legal name of eighth inventor KWAK, Young Hoon	
Eighth inventor's signature Kwak	Date 2013. 4. 8.

Legal name of ninth inventor HEO, Chang Jae	
Ninth inventor's signature <i>Heo Chang Jae</i>	Date <i>2013. 4. 8</i>